

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2000-214585

(43)Date of publication of application : 04.08.2000

(51)Int.Cl.

G03F 7/037
C08G 73/10
C08K 3/04
C08L 79/08
C09D 5/00
G03F 7/028
H01L 21/027

(21)Application number : 11-015176

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(22)Date of filing : 25.01.1999

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(54) PHOTSENSITIVE RESIN COMPOSITION

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a negative photosensitive resin composition applicable to manufacture semiconductor elements and circuit boards and the like and high in sensitivity and resolution and superior in heat resistance by incorporating a polyamic acid or polyimide each having cis-diene structures on the side chains and an oxygen sensitizing dye.

SOLUTION: This photosensitive resin composition contains a oxygen sensitizer and polyamic acid or polyimide each substituted by the cis-diene structures represented by the formula in which at least one of R1-R4 is a monovalent organic group having the cis-diene structure and each of the others is, independently, an H atom or a hydroxyl or carboxyl or 1-20C alkyl or such alkoxy group. The cis-diene structure is a furan or thiophene or pyrrole, and the oxygene sensitizer is a flarene compound and the structural units of the formula amount to ≥ 30 mol. % of the total diamine structural units, thus the resin layer to be enhanced in sensitivity and resolution and heat resistance is obtained.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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